



SOD962

DSN0603-2: leadless ultra small package; 2 terminals; body
0.6 x 0.3 x 0.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOD2
Package type industry code	DSN0603-2
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-7-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.275	-	0.3	0.325	mm
E	package width	0.575	-	0.6	0.625	mm
A	seated height	0.28	-	0.3	0.32	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

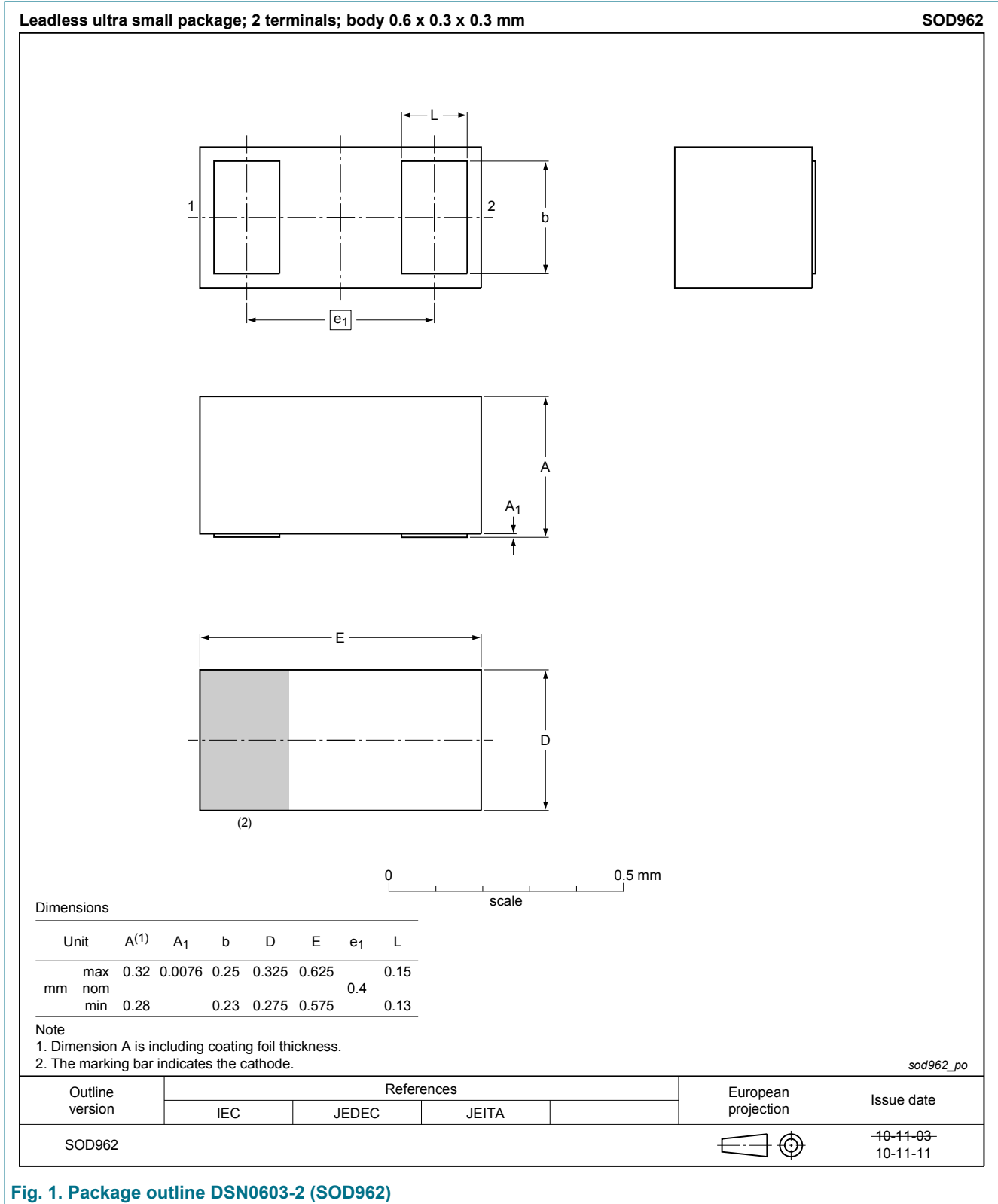


Fig. 1. Package outline DSN0603-2 (SOD962)

3. Soldering

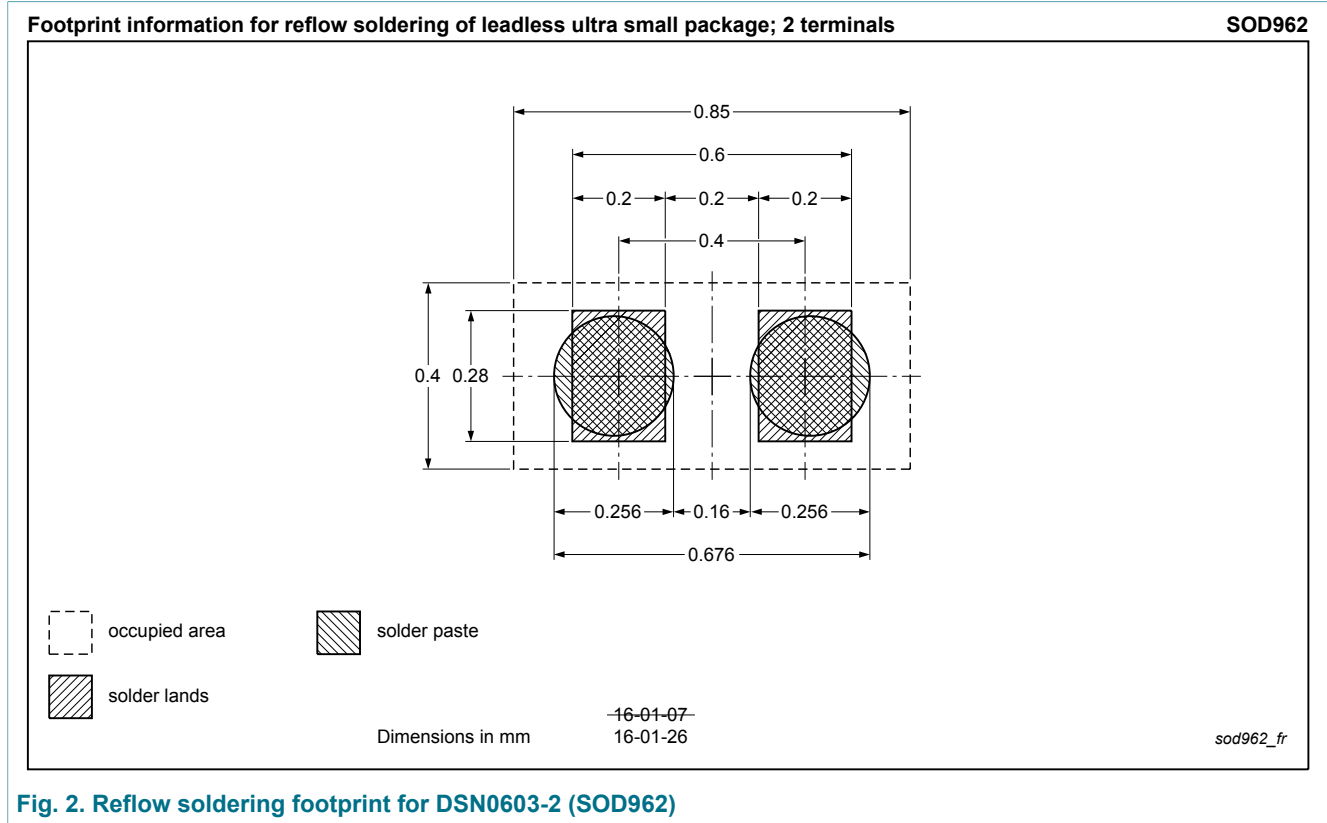


Fig. 2. Reflow soldering footprint for DSN0603-2 (SOD962)

4. Legal information

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Date of release: 8 February 2016
